## MSG33001

### SiGe HBT type

#### For low-noise RF amplifier

#### ■ Features

- Compatible between high breakdown voltage and high cutoff frequency
- Low-noise, high-gain amplification
- Suitable for high-density mounting and downsizing of the equipment for Ultraminiature package
   0.8 mm × 1.2 mm (height 0.52 mm)

## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit					
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	9	V					
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	6	V					
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	1	V					
Collector current	$I_{C}$	30	mA					
Collector power dissipation *	P <sub>C</sub>	100	mW					
Junction temperature	T <sub>j</sub>	125	°C					
Storage temperature	T <sub>stg</sub>	-55 to +125	°C					

Note) \*: Copper plate at the collector is  $5.0 \text{ mm}^2$  on substrate at  $10 \text{ mm} \times 12 \text{ mm} \times 0.8 \text{ mm}$ .

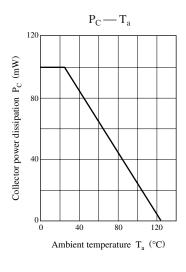
# 

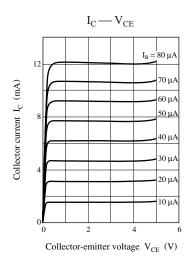
Marking Symbol: 5S

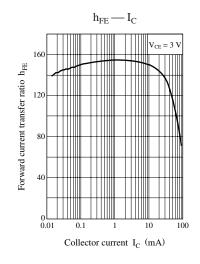
#### $\blacksquare$ Electrical Characteristics $~T_a = 25^{\circ}C \pm 3^{\circ}C$

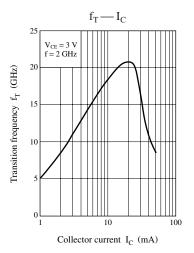
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 9 \text{ V}, I_{E} = 0$			1	nA
Collector-emitter cutoff current (Base open)	I <sub>CEO</sub>	$V_{CE} = 6 \text{ V}, I_{B} = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 1 \text{ V}, I_C = 0$			1	μΑ
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = 3 \text{ V}, I_{C} = 3 \text{ mA}$	100		220	_
Transition frequency	$f_T$	$V_{CE} = 3 \text{ V}, I_{C} = 10 \text{ mA}, f = 2 \text{ GHz}$		19		GHz
Forward transfer gain	$ S_{21e} ^2$	$V_{CE} = 3 \text{ V}, I_{C} = 10 \text{ mA}, f = 2 \text{ GHz}$	9.0	11.0		dB
Noise figure	NF	$V_{CE} = 3 \text{ V}, I_{C} = 3 \text{ mA}, f = 2 \text{ GHz}$		1.4	2.0	dB
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 3 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		0.3	0.6	pF
(Common base, input open circuited)						

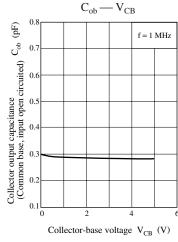
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

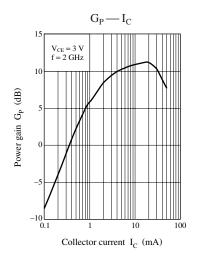


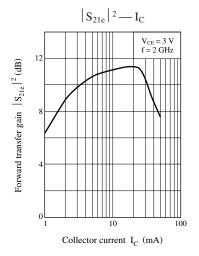


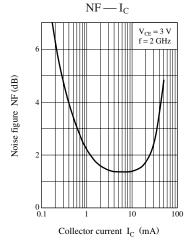


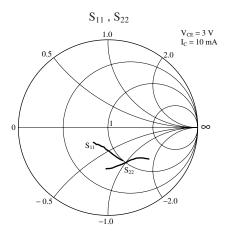


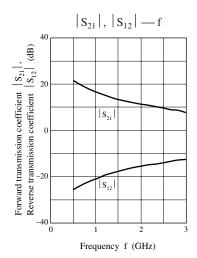












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